

II. CLAIMS

1-10. (Previously Cancelled)

11. (Previously Presented) Optoelectronic device having a first printed-circuit element, on which is mounted an optic emitter and/or receiver, having openings to receive centering pins of a complementary optic connector to be mounted facing said optic emitter and/or receiver, said optoelectronic device being provided further with a heatsink, wherein said first printed-circuit element is applied against a first face of said heatsink, and wherein a flexible printed-circuit segment connects said first printed circuit element to a second printed-circuit element wherein one of said first and second printed-circuit elements is rigid, this second printed-circuit element being applied against a second face of the heatsink, this second face being separate from the first face.

12. (Previously Presented) Optoelectronic device according to claim 11, wherein said openings comprise holes located on said first printed circuit element.

13. (Previously Presented) Device according to claim 11, wherein said first face is a secant relative to the second face, and in that said flexible printed-circuit segment forms an elbow.

14. (Previously Presented) Device according to claim 13, wherein said elbow forms an angle of approximately 90 degrees.

15. (Previously Presented) Device according to claim 11, wherein said first face and said second face are part of two planes intersecting each other, and in that said flexible printed-circuit segment forms an elbow linking said first and second printed circuit elements.

16. (Previously Cancelled)

17. (Previously Presented) Device according to claim 11, wherein at least one of said first and second printed-circuit elements is flexible and forms a single printed circuit with said printed-circuit flexible segment.

18. (Previously Presented) Device according to claim 11, wherein the heatsink has two receptacles on its first face, these receptacles being at least a part of said openings and providing holding of the centering pins.

19. (Previously Presented) Device according to claim 11, wherein said optic receiver is positioned between said openings.

20. (Previously Presented) Device according to claim 12, wherein said optic receiver is positioned between said holes.

21. (Previously Presented) Device according to claim 11, wherein said second printed-circuit element has microbeads for connection with another device such as a motherboard.

22. (Previously Presented) Device according to claim 21, wherein said second printed-circuit element has contact areas receiving contact studs of an intermediate connector coupling said second element of said printed circuit to an electronic board.

23. (Previously Presented) Optoelectronic device according to claim 21, wherein said openings to receive said centering pins comprise holes located on said first printed circuit element.

24. (Previously Presented) Device according to claim 21, wherein said first face and said second face are part of two planes intersecting each other, and in that said flexible printed-circuit segment forms an elbow linking said first and second printed circuit elements.

25. (Previously Presented) Device according to claim 21, wherein at least one of the first and second printed-circuit elements is rigid.

26. (Previously Presented) Device according to claim 21, wherein at least one of the first and second printed-circuit elements is flexible and forms a single printed circuit with the printed-circuit flexible segment.

27. (Previously Presented) Device according to claim 21, wherein the heatsink has two receptacles on its first face, these receptacles being positioned facing said openings and providing holding of the centering pins.

28. (Previously Presented) Device according to claim 21, wherein said optic receiver is positioned between said openings.

29. (Previously Presented) Device according to claim 21, wherein said second printed-circuit element has microbeads for connection with another device.

30. (Previously Presented) Device according to claim 21, wherein said intermediate connector is made up of two elements interconnectable by complementary coupling terminations on an interconnection face, at least the element in contact with the second printed-circuit element being provided with solder microbeads on its face for connection with the second printed-circuit element.

31. (Previously Presented) The device of claim 29 wherein another device comprises a mother board.

32. (Previously Presented) The optoelectronic device of claim 11 wherein the first printed circuit element is rigid.

33. (Previously Presented) The optoelectronic device of claim 11 wherein the second printed circuit element is rigid.

34. (Previously Presented) The device of claim 11 wherein the first printed circuit element and the second printed circuit element are discontinuous segments joined together by the flexible printed-circuit segment.